



GaAs pHEMT MMIC LOW NOISE AMPLIFIER, 24 - 43.5 GHz

Typical Applications

This HMC1040LP3BE is ideal for:

- Point-to-Point Radios
- Test Instrumentation
- SatCom Transponders & VSAT
- · Industrial Sensors
- EW & ECM Subsystems

Features

Low Noise Figure: 2.2 dB

High Gain: 23 dB

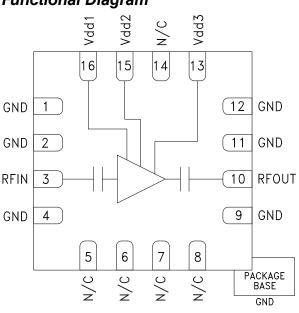
P1dB Output Power: +12 dBm Single Supply: +2.5V @ 70 mA

Output IP3: +22 dBm

50 Ohm Matched Input/Output

16 Lead 3x3 mm SMT Package: 16mm²

Functional Diagram



General Description

The HMC1040LP3CE is a self-biased GaAs MMIC Low Noise Amplifier housed in a leadless 3x3 mm plastic surface mount package. The amplifier operates between 24 and 43.5 GHz, delivering 23 dB of small signal gain, 2.2 dB noise figure, and output IP3 of +22 dBm, while requiring only 70 mA from a +2.5 V supply. The P1dB output power of +12 dBm enables the LNA to function as a LO driver for many of Hittite's balanced, I/Q and image reject mixers. The HMC1040LP3CE features I/Os that are DC blocked and internally matched to 50 Ohms, and is ideal for high capacity microwave radios and VSAT applications.

Electrical Specifications, $T_A = +25^{\circ}$ C, Vdd1 = Vdd2 = Vdd3 = +2.5V, Idd = 70 mA

| Parameter | Min. | Тур. | Max. | Min. | Тур. | Max. | Min. | Тур. | Max. | Units |
|--------------------------------------|-----------|-------|-------------|------|-------------|------|------|-------|------|--------|
| Frequency Range | 24 - 27.5 | | 27.5 - 33.5 | | 33.5 - 43.5 | | | GHz | | |
| Gain [1] | 22 | 25 | | 20 | 23 | | 17 | 20 | | dB |
| Gain Variation over Temperature | | 0.022 | | | 0.021 | | | 0.021 | | dB /°C |
| Noise Figure [1] | | 2.7 | 3.2 | | 2.2 | 2.7 | | 2.7 | 3.2 | dB |
| Input Return Loss | | 11 | | | 12 | | | 10 | | dB |
| Output Return Loss | | 16 | | | 13 | | | 10 | | dB |
| Output Power for 1 dB Compression | | 12 | | | 12 | | | 12 | | dBm |
| Saturated Output Power (Psat) | | 14 | | | 14 | | | 14 | | dBm |
| Output Third Order Intercept (IP3) | | 22 | | | 22 | | | 24 | | dBm |
| Supply Current (Idd) (Vdd = 2.5V) | | 70 | 85 | | 70 | 85 | | 70 | 85 | mA |
| [1] Board loss subtracted out. | | | | | | | | • | | |

HMC1040* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS -

View a parametric search of comparable parts.

EVALUATION KITS

• HMC1040LP3C Evaluation Board

DOCUMENTATION

Application Notes

- AN-1363: Meeting Biasing Requirements of Externally Biased RF/Microwave Amplifiers with Active Bias Controllers
- Broadband Biasing of Amplifiers General Application Note
- MMIC Amplifier Biasing Procedure Application Note
- Thermal Management for Surface Mount Components General Application Note

Data Sheet

HMC1040 Data Sheet

TOOLS AND SIMULATIONS 🖳

HMC1040 S-Parameters

REFERENCE MATERIALS 🖵

Quality Documentation

- Package/Assembly Qualification Test Report: LP3, LP4, LP5 & LP5G (QTR: 2014-00145)
- Semiconductor Qualification Test Report: PHEMT-L (QTR: 2013-00266)

DESIGN RESOURCES 🖵

- · HMC1040 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC1040 EngineerZone Discussions.

SAMPLE AND BUY 🖳

Visit the product page to see pricing options.

TECHNICAL SUPPORT 🖵

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK 🖳

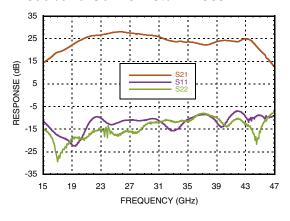
Submit feedback for this data sheet.



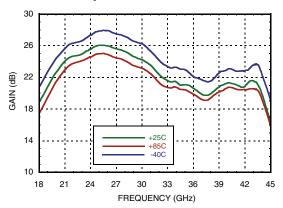


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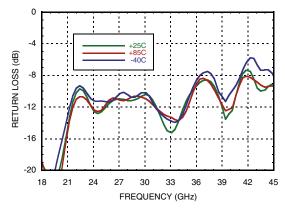
Broadband Gain & Return Loss [1]



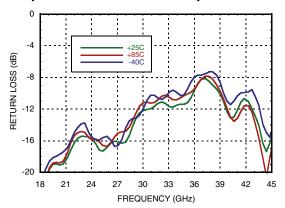
Gain vs. Temperature [1]



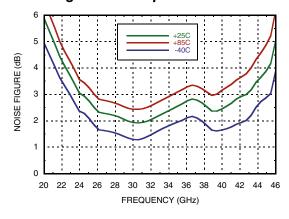
Input Return Loss vs. Temperature



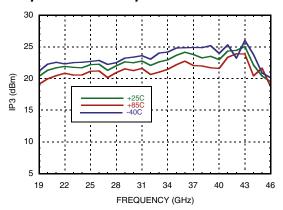
Output Return Loss vs. Temperature



Noise Figure vs. Temperature [1]



Output IP3 vs. Temperature



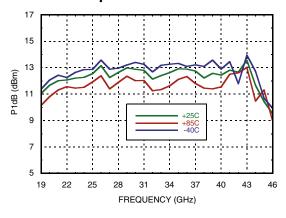
[1] Board loss subtracted out, gain only.



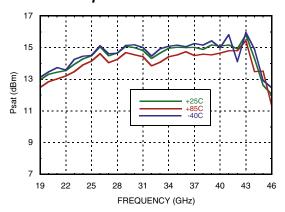


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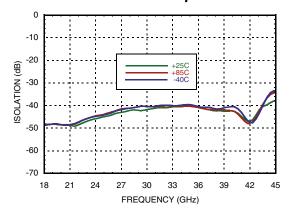
P1dB vs. Temperature



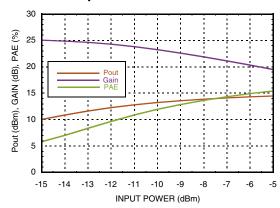
Psat vs. Temperature



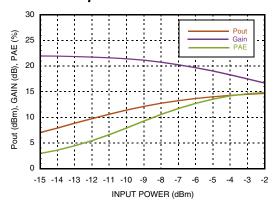
Reverse Isolation vs. Temperature



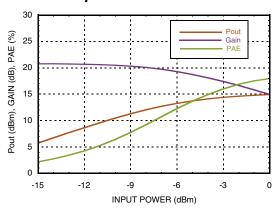
Power Compression @ 25 GHz



Power Compression @ 33 GHz



Power Compression @ 42 GHz

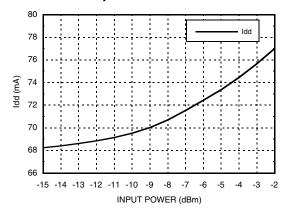






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Current vs. Input Power @ 33 GHz



Absolute Maximum Ratings

| Drain Bias Voltage | +4V |
|---|----------------|
| RF Input Power | +5 dBm |
| Channel Temperature | 175 °C |
| Continuous Pdiss (T = 85 °C) (derate 5.46 mW/°C above 85 °C) | 0.49 W |
| Thermal Resistance (Channel to ground paddle) | 183 °C/W |
| Storage Temperature | -65 to +150 °C |
| Operating Temperature | -40 to +85 °C |
| ESD Sensitivity (HBM) | Class 0, 100 V |



ELECTROSTATIC SENSITIVE DEVICE **OBSERVE HANDLING PRECAUTIONS**

.016 [0.40] REF

.008 [0.20] MIN

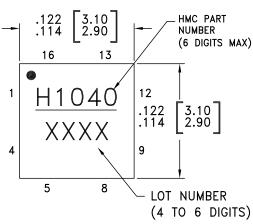
PIN 1

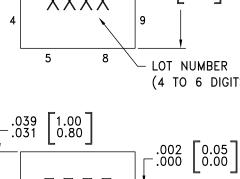
EXPOSED

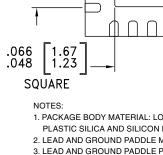
GROUND

PADDLE

Outline Drawing







- 1 PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
- 2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY.

BOTTOM VIEW

- 3. LEAD AND GROUND PADDLE PLATING: 100% MATTE TIN
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 6. PAD BURR LENGTH SHALL BE 0.15mm MAX. PAD BURR HEIGHT SHALL
- 7. PACKAGE WARP SHALL NOT EXCEED 0.05mm
- 8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 9. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND

Package Information

.003[0.08]|C

| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking [2] |
|--------------|--|---------------|------------|----------------------|
| HMC1040LP3CE | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 [1] | <u>H1040</u> XXXX |

- [1] Max peak reflow temperature of 260 °C
- [2] 4-Digit lot number XXXX

SEATING PLANE

-C-



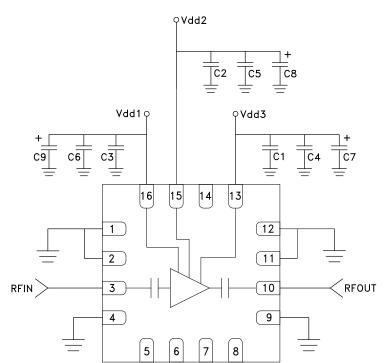


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Pin Descriptions

| Pin Number | Function | Description | Interface Schematic |
|-----------------------|------------------|--|---|
| 1, 2, 4, 9, 11, 12 | GND | These pins and package bottom must be connected to RF/DC ground. | GND |
| 3 | RFIN | This pin AC coupled and matched to 50 Ohms | RFIN Ο ESD(5kΩ) |
| 5-8, 14 | N/C | The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally. | |
| 10 | RFOUT | This pin AC coupled and matched to 50 Ohms | $\begin{array}{c c} & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & \\ & & & \\ & \\ & & \\ & & \\ & & \\ & \\ & & \\ & & \\ & & \\ & & \\ & & \\ & & \\ & & \\ & & \\ & & \\ & & \\ &$ |
| 13, 15, 16 | Vdd3, Vdd2, Vdd1 | Drain bias voltages for the amplifier. See Application Circuit for required external componnets. | Vdd1,2,3 |

Application Circuit



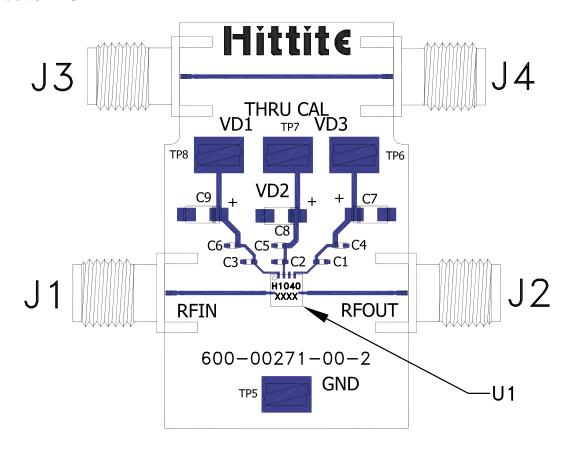
| Capacitor | Value |
|-----------|--------|
| C1 - C3 | 100 pF |
| C4 - C6 | 10 nF |
| C7 - C9 | 4.7 μF |





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Evaluation PCB



List of Material for Evaluation PCB EVAL01-HMC1040LP3CE [1]

| Item | Description |
|---------|-------------------------------|
| J1-J4 | 2.92 mm Connectors |
| TP5-TP8 | Test Points DC Pin |
| C1 - C3 | 100 pF Capacitor, 0402 Pkg. |
| C4 - C6 | 10 nF Capacitor, 0402 Pkg. |
| C7 - C9 | 4.7 μF Capacitor, Tantalum |
| U1 | HMC1040LP3CE Amplifier |
| PCB [2] | 600-00271-00-2 Evaluation PCB |

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350 or Arlon 25FR